

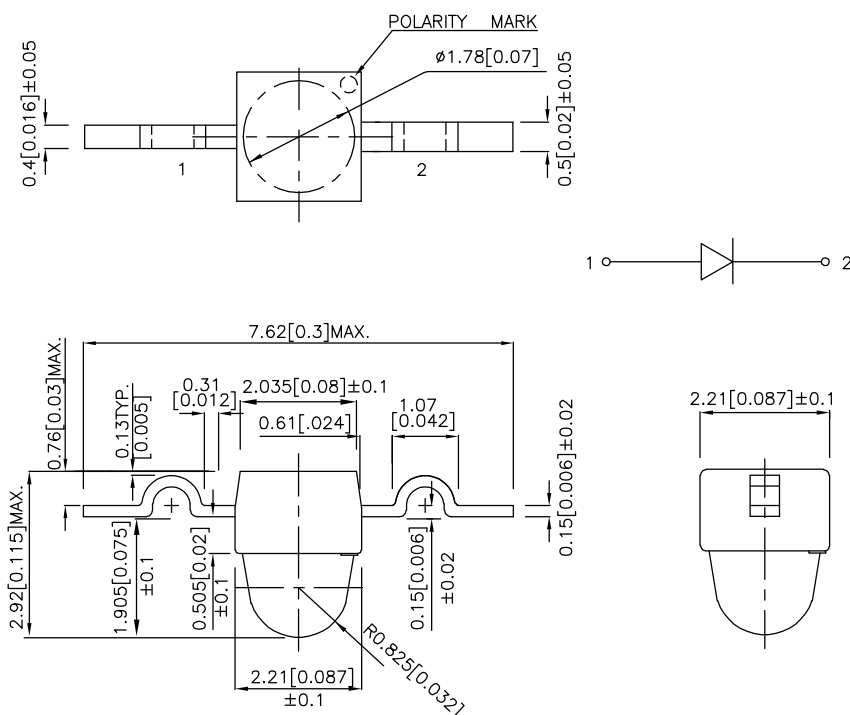
## Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- YOKE LEAD.
- LONG LIFE-SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.
- RoHS COMPLIANT.

### Description

The Super Bright Orange device is made with DH InGaAlP (on GaAs substrate) light emitting diode chip.

## Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
KM-27SEC-08	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	480	1300	20°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

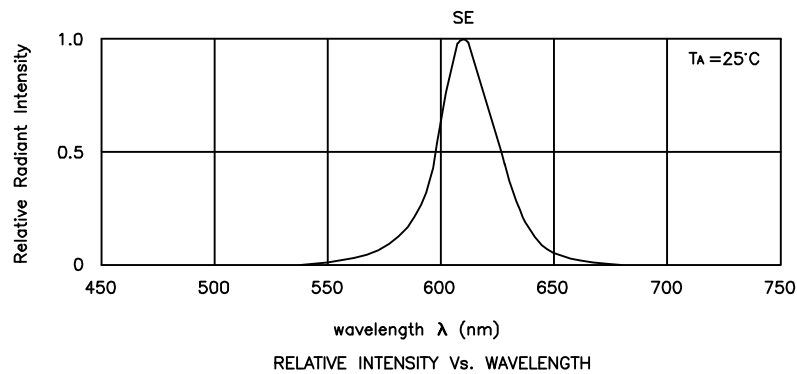
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Super Bright Orange	610		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominant Wavelength	Super Bright Orange	601		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Super Bright Orange	29		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Orange	30		pF	V <sub>F</sub> =0V; f=1MHz
V <sub>F</sub>	Forward Voltage	Super Bright Orange	2.0	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Orange		10	uA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

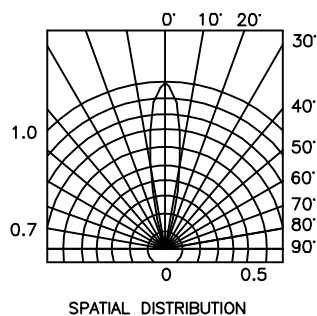
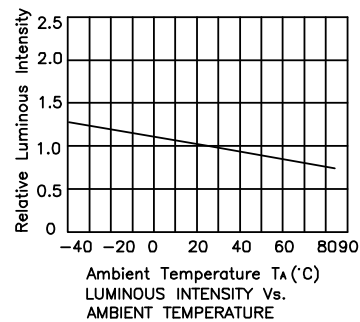
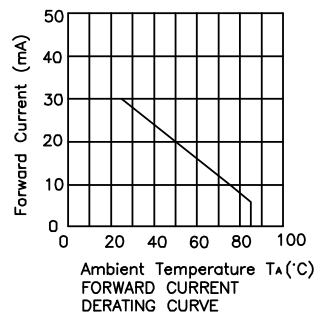
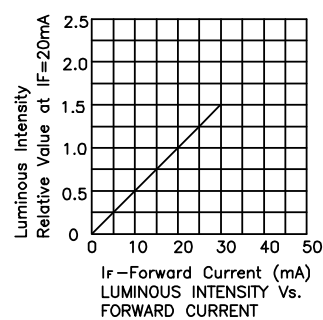
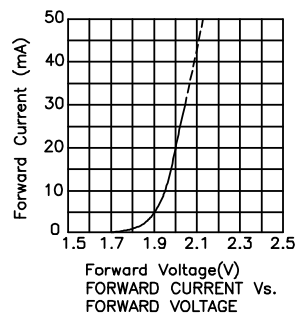
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



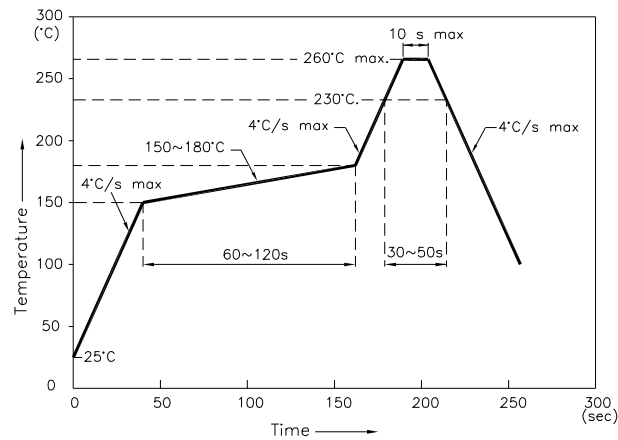
Super Bright Orange

KM-27SEC-08



## KM-27SEC-08

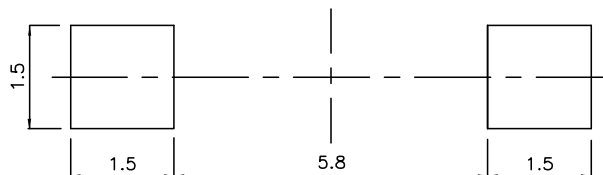
Reflow Soldering Profile For Lead-free SMT Process.



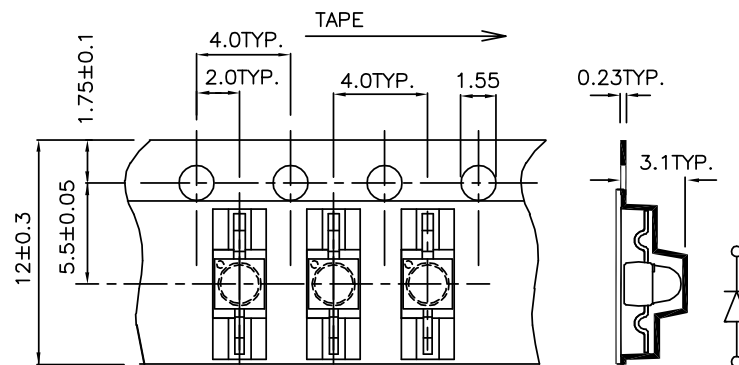
### NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (+/-5^{\circ}\text{C})$ . The maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

## Recommended Soldering Pattern (Units : mm)



## Tape Specifications (Units : mm)



### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength:  $\pm 1\text{nm}$
2. Luminous Intensity:  $\pm 15\%$
3. Forward Voltage:  $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.